

FDMC4D9P20X8

P-Channel Power Trench[®] MOSFET

–20 V, –75 A, 4.9 mΩ

General Description

This P-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench[®] process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Features

- Max $r_{DS(on)}$ = 4.9 mΩ at $V_{GS} = -4.5$ V, $I_D = -18$ A
- Max $r_{DS(on)}$ = 16.4 mΩ at $V_{GS} = -1.8$ V, $I_D = -9$ A
- High Performance Trench Technology for Extremely Low $r_{DS(on)}$
- High Power and Current Handling Capability in a Widely Used Surface Mount Package
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Load Switch
- Battery Management
- Power Management
- Reverse Polarity Protection

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	–20	V
V_{GS}	Gate to Source Voltage	±12	V
I_D	Drain Current: Continuous, $T_C = 25^\circ\text{C}$ (Note 5) Continuous, $T_C = 100^\circ\text{C}$ (Note 5) Continuous, $T_A = 25^\circ\text{C}$ (Note 1a) Pulsed (Note 4)	–75 –47 –18 –335	A
E_{AS}	Single Pulse Avalanche Energy (Note 3)	54	mJ
P_D	Power Dissipation: $T_C = 25^\circ\text{C}$ $T_A = 25^\circ\text{C}$ (Note 1a)	40 2.4	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	–55 to +150	$^\circ\text{C}$

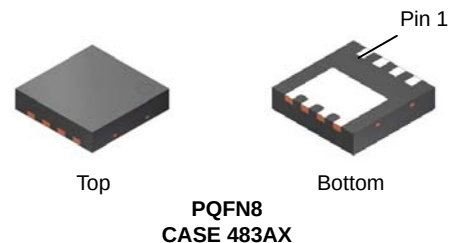
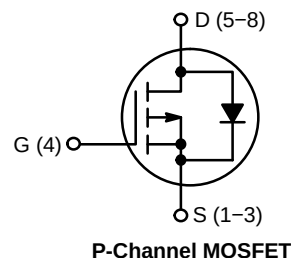
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



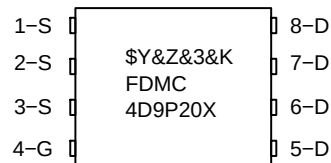
ON Semiconductor[®]

www.onsemi.com

V_{DS}	$R_{DS(ON)}$ MAX	I_D MAX
–20 V	4.9 mΩ @ –4.5 V	–75 A
	6.5 mΩ @ –2.5 V	
	16.4 mΩ @ –1.8 V	



MARKING DIAGRAM



\$Y = ON Semiconductor Logo
&Z = Assembly Plant Code
&3 = Data Code (Year & Week)
&K = Lot
FDMC4D9P20X8 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

FDMC4D9P20X8

THERMAL CHARACTERISTICS

Symbol	Parameter	FDMC4D9P20X8	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.1	$^{\circ}\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
--------	-----------	-----------------	------	------	------	-------

OFF CHARACTERISTICS

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = -250\ \mu\text{A}$, $V_{GS} = 0\ \text{V}$	-20			V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C		-15		$\text{mV}/^{\circ}\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16\ \text{V}$, $V_{GS} = 0\ \text{V}$			-1	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 12\ \text{V}$, $V_{DS} = 0\ \text{V}$			± 100	nA

ON CHARACTERISTICS

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = -250\ \mu\text{A}$	-0.4	-0.7	-1.6	V
$\Delta V_{GS(th)}/\Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, referenced to 25°C		4		$\text{mV}/^{\circ}\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = -4.5\ \text{V}$, $I_D = -18\ \text{A}$		3.3	4.9	$\text{m}\Omega$
		$V_{GS} = -2.5\ \text{V}$, $I_D = -11\ \text{A}$		4.1	6.5	
		$V_{GS} = -1.8\ \text{V}$, $I_D = -9\ \text{A}$		6.2	16.4	
		$V_{GS} = -4.5\ \text{V}$, $I_D = -18\ \text{A}$, $T_J = 125^{\circ}\text{C}$		4.5	6.8	
g_{FS}	Forward Transconductance	$V_{DS} = -5\ \text{V}$, $I_D = -18\ \text{A}$		113		S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = -10\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$		7535	10550	pF
C_{oss}	Output Capacitance			1100	1540	pF
C_{rss}	Reverse Transfer Capacitance			1040	1455	pF
R_g	Gate Resistance		0.1	4.5	10	Ω

SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -10\ \text{V}$, $I_D = -18\ \text{A}$, $V_{GS} = -4.5\ \text{V}$, $R_G = 6\ \Omega$		13	23	ns
t_r	Rise Time			17	31	ns
$t_{d(off)}$	Turn-Off Delay Time			312	499	ns
t_f	Fall Time			176	282	ns
Q_g	Total Gate Charge	$V_{GS} = 0\ \text{V}$ to $-4.5\ \text{V}$, $V_{DD} = -10\ \text{V}$, $I_D = -18\ \text{A}$		78	109	nC
		$V_{GS} = 0\ \text{V}$ to $-2.5\ \text{V}$, $V_{DD} = -10\ \text{V}$, $I_D = -18\ \text{A}$		50	70	nC
Q_{gs}	Gate to Source Charge	$V_{DD} = -10\ \text{V}$, $I_D = -18\ \text{A}$		12		nC
Q_{gd}	Gate to Drain "Miller" Charge	$V_{DD} = -10\ \text{V}$, $I_D = -18\ \text{A}$		24		nC

DRAIN-SOURCE DIODE CHARACTERISTICS

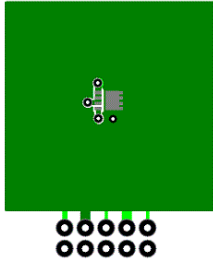
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\ \text{V}$, $I_S = -18\ \text{A}$ (Note 2)		-0.7	-1.2	V
		$V_{GS} = 0\ \text{V}$, $I_S = -2\ \text{A}$ (Note 2)		-0.6	-1.2	
t_{rr}	Reverse Recovery Time	$I_S = -18\ \text{A}$, $di/dt = 100\ \text{A}/\mu\text{s}$		41	66	ns
Q_{rr}	Reverse Recovery Charge			22	35	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

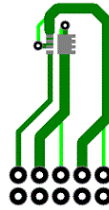
FDMC4D9P20X8

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta CA}$ is determined by the user's board design.

NOTES:



a) 53 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0 %
3. E_{AS} of 54 mJ is based on starting $T_J = 25$ °C, $L = 3$ mH, $I_{AS} = -6$ A, $V_{DD} = -20$ V, $V_{GS} = -10$ V.
4. Pulsed I_d please refer to Fig 11 SOA graph for more details.
5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC4D9P20X8	FDMC4D9P20X8	PQFN8 (Pb Free)	13"	12 mm	3000 Units

TYPICAL CHARACTERISTICS

($T_J = 25^\circ\text{C}$ unless otherwise noted)

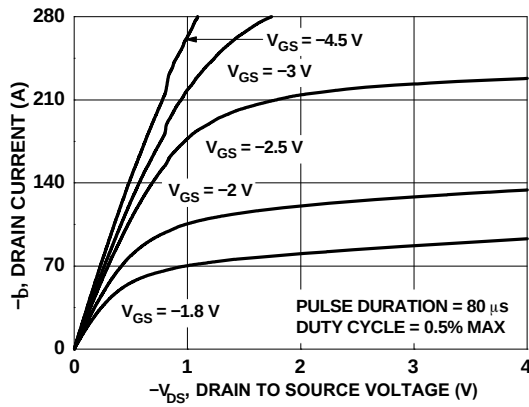


Figure 1. On-Region Characteristics

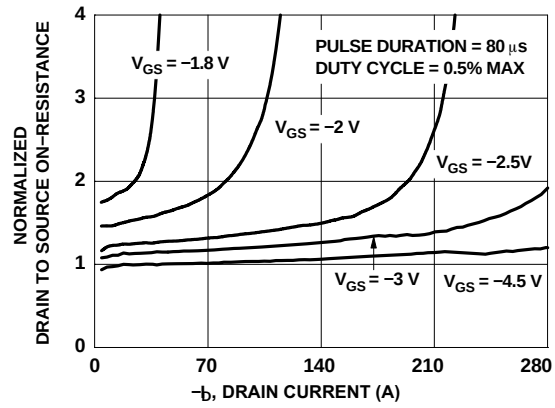


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

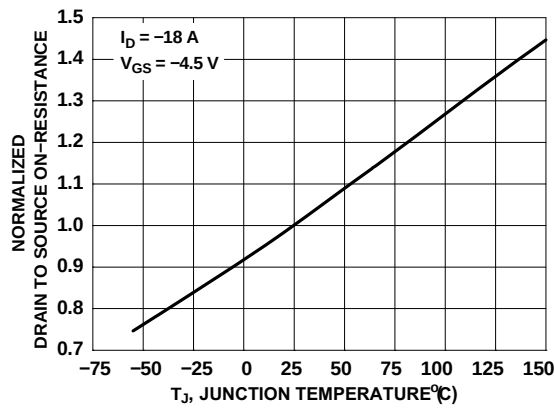


Figure 3. Normalized On-Resistance vs Junction Temperature

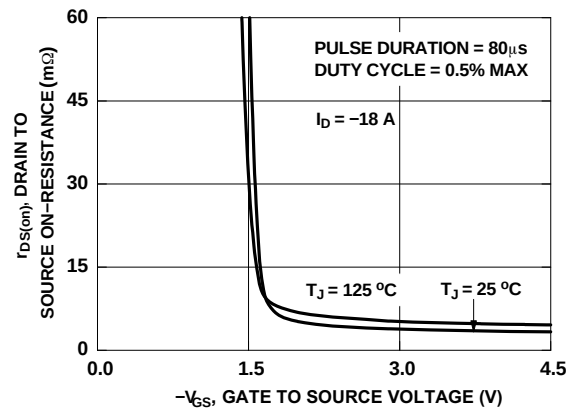


Figure 4. On-Resistance vs Gate to Source Voltage

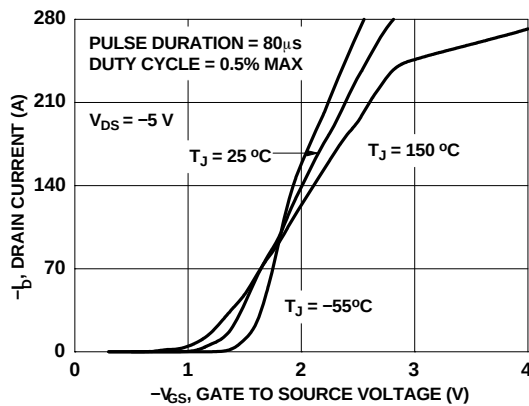


Figure 5. Transfer Characteristics

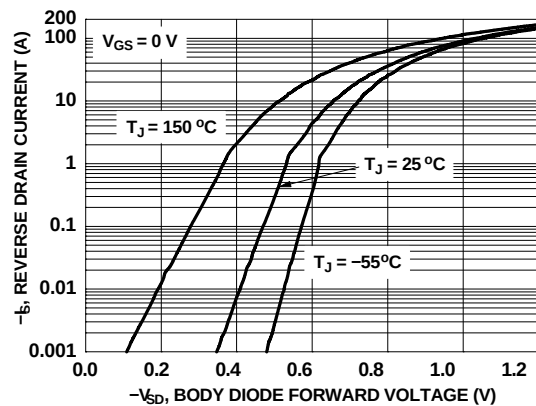


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

FDMC4D9P20X8

TYPICAL CHARACTERISTICS

($T_J = 25^\circ\text{C}$ unless otherwise noted)

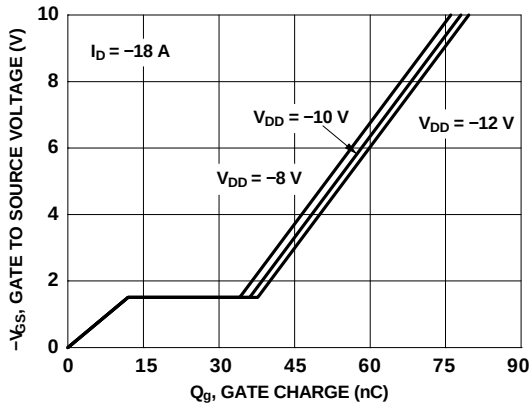


Figure 7. Gate Charge Characteristics

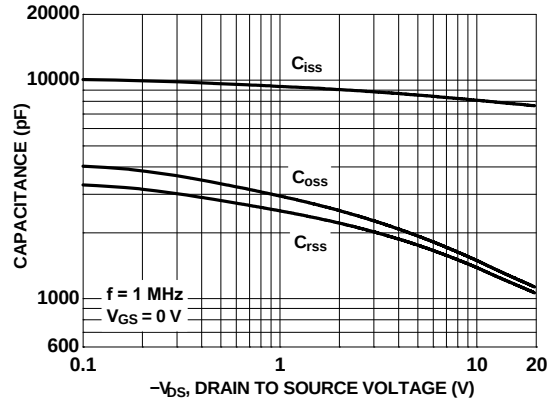


Figure 8. Capacitance vs Drain to Source Voltage

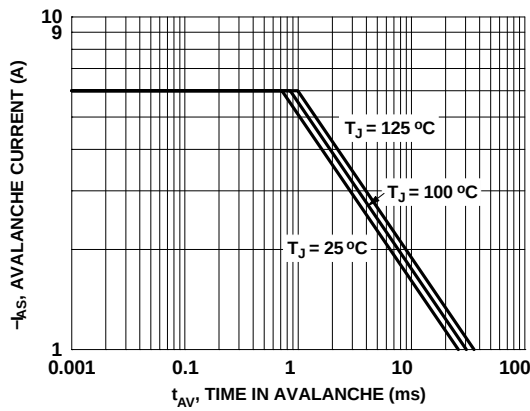


Figure 9. Unclamped Inductive Switching Capability

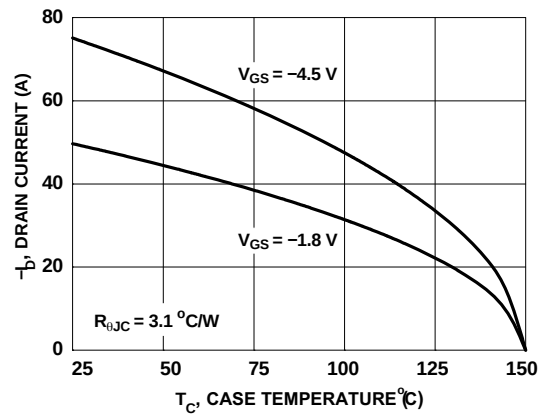


Figure 10. Maximum Continuous Drain Current vs Case Temperature

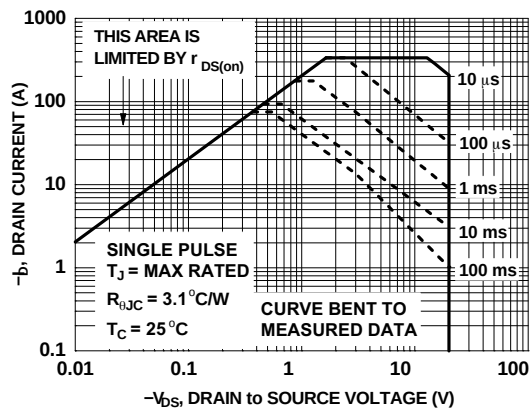


Figure 11. Forward Bias Safe Operating Area

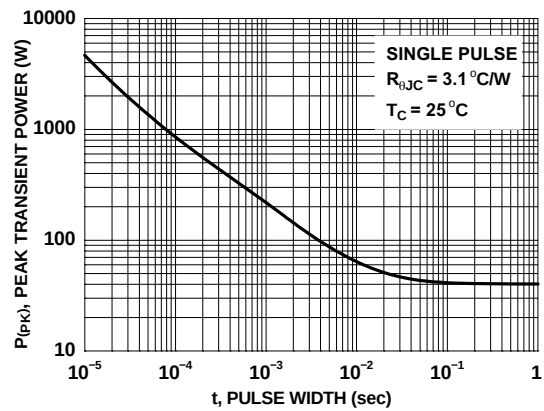


Figure 12. Single Pulse Maximum Power Dissipation

FDMC4D9P20X8

TYPICAL CHARACTERISTICS

($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

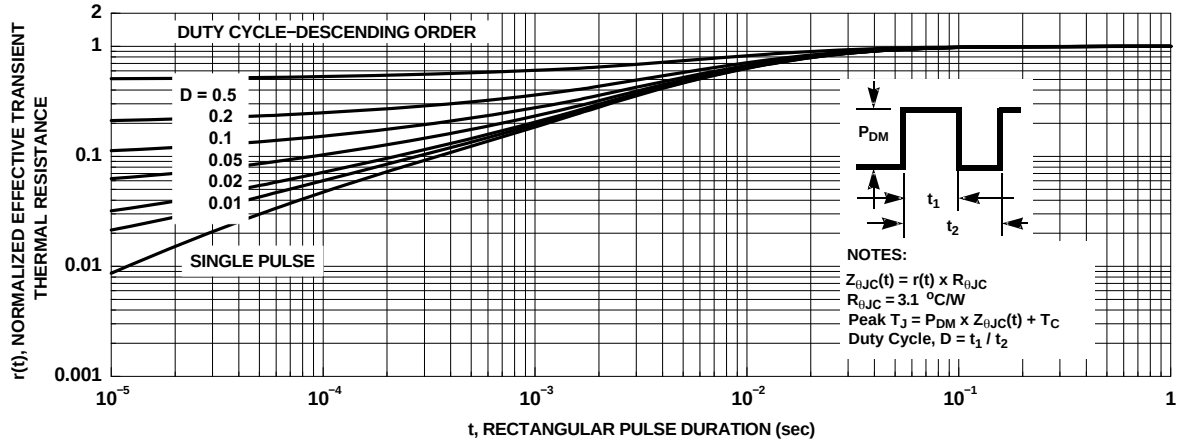
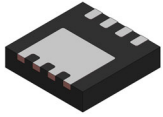


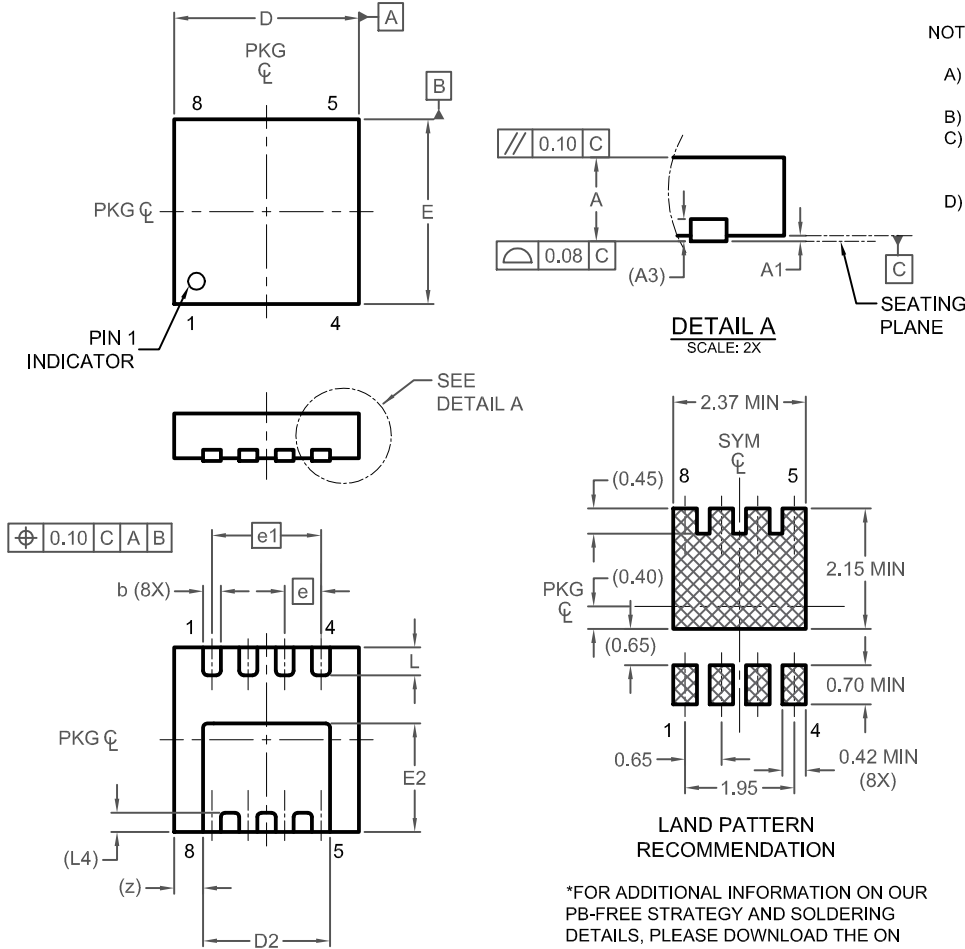
Figure 13. Junction-to-Case Transient Thermal Response Curve

POWERTRENCH is a registered trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.



PQFN8 3.3X3.3, 0.65P
CASE 483AX
ISSUE B

DATE 24 JUN 2022



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE:
 JEDEC MO-240, ISSUE A, VAR. BA,
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS DO NOT INCLUDE BURRS
 OR MOLD FLASH. MOLD FLASH OR
 BURRS DOES NOT EXCEED 0.10MM.
 D) DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M-2009.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.20 REF		
b	0.27	0.32	0.37
D	3.20	3.30	3.40
D2	2.17	2.27	2.37
E	3.20	3.30	3.40
E2	1.84	1.94	2.04
e	0.65 BSC		
e1	1.95 BSC		
L	0.40	0.50	0.60
L4	0.34 REF		
z	0.52 REF		

*FOR ADDITIONAL INFORMATION ON OUR
 PB-FREE STRATEGY AND SOLDERING
 DETAILS, PLEASE DOWNLOAD THE ON
 SEMICONDUCTOR SOLDERING AND
 MOUNTING TECHNIQUES REFERENCE
 MANUAL, SOLDERM/D.

DOCUMENT NUMBER:	98AON13673G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	PQFN8 3.3X3.3, 0.65P	PAGE 1 OF 1

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales

